

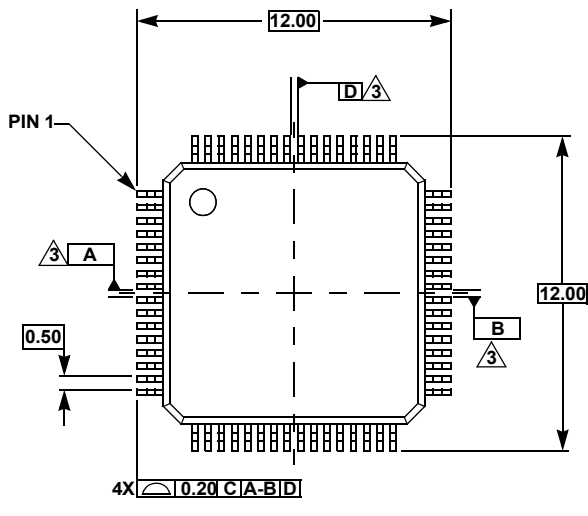
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

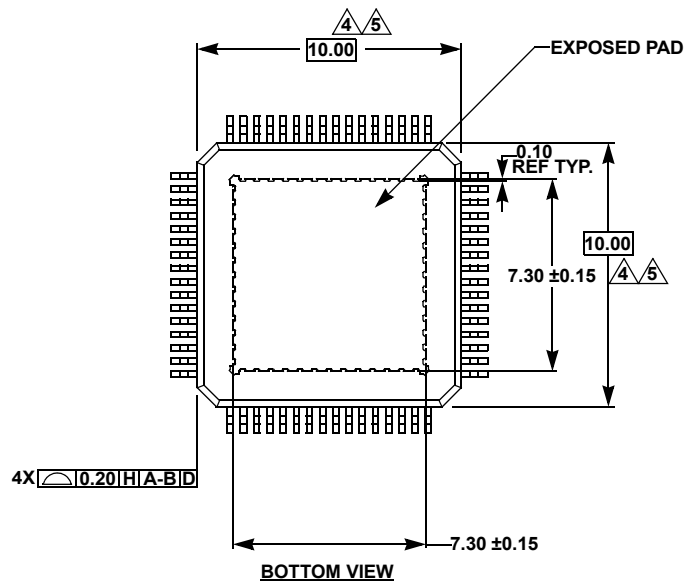
Q64.10x10J

64 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE WITH EXPOSED PAD (EP-TQFP)

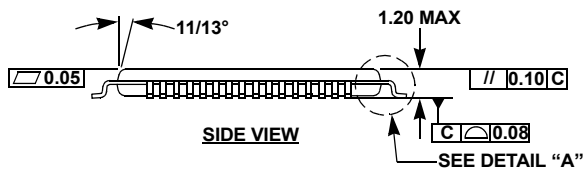
Rev 0, 5/16



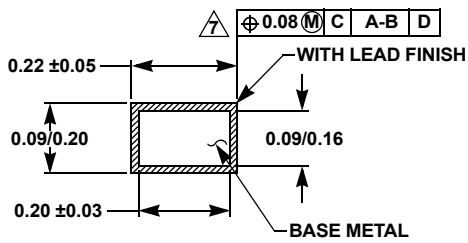
TOP VIEW



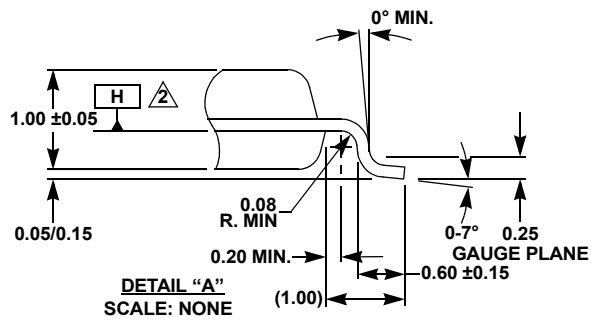
BOTTOM VIEW



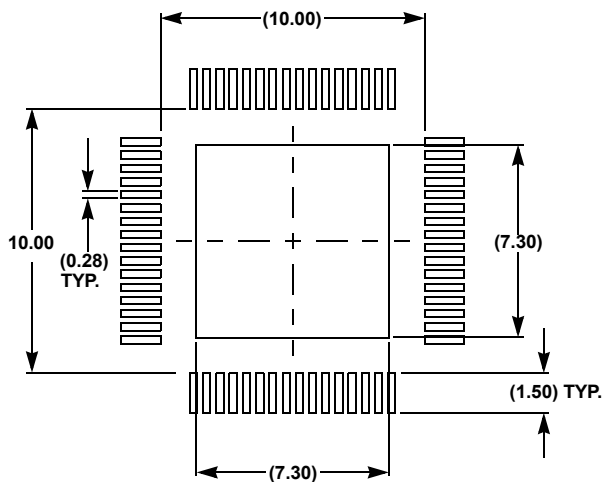
SIDE VIEW



LEAD CROSS-SECTION VIEW



DETAIL "A"  
SCALE: NONE



RECOMMENDED LAND PATTERN

### NOTES:

1. All dimensioning and tolerancing conform to ANSI Y14.5-1982.
2. Datum plane H located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
3. Datums A-B and D to be determined at centerline between leads where leads exit plastic body at datum plane H.
4. Dimensions do not include mold protrusion. Allowable mold protrusion is 0.254mm on these dimensions.
5. These dimensions to be determined at datum plane H.
6. Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
7. Lead width dimension does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total in excess of the dimension at maximum material condition. Dambar cannot be located on the lower radius or the foot.
8. Controlling dimension: millimeter.
9. This outline conforms to JEDEC publication 95 registration MS-026, variation ACD.
10. Dimensions in ( ) are for reference only.